DONGGUAN NANJING ELECTRONICS LTD.,

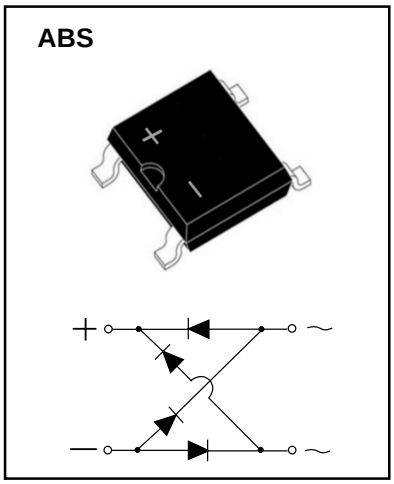
ABS Plastic-Encapsulate Bridge Rectifier

RABS202 THRU RABS210

FAST RECOVERY SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

Features

- $I_{F(AV)}$ 2A
- V_{RRM} 200V-1000V
- High surge current capability
- Glass passivated chip



Applications

- General purpose 1 phase Bridge rectifier applications

Marking

- RABS2XX

X：From 02 To 10

Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions		RABS				
					202	204	206	208	210
Repetitive Peak Reverse Voltage	V_{RRM}	V			200	400	600	800	1000
Maximum RMS Voltage	V_{RMS}	V			140	280	420	560	700
Average Rectified Output Current	I_O	A	60Hz sine wave, R-load,Ta=115℃	On alumina substrate	2.0				
Surge(Non-repetitive)Forward Current	I_{FSM}	A	8.3ms sine wave, 1 cycle, T_j=25℃		75				
			1.0ms sine wave, 1 cycle, T_j=25℃		120				
Current Squared Time	I^2t	A^2S	1ms≤t<8.3ms Tj=25℃， Rating of per diode		5.0				
Maximum Reverse Recovery Time	T_{RR}	ns	Measured with IF=0.5A,IR=1A,IRR=0.25A		500				
Operation Junction and Storage Temperature Range	T_J,T_{stg}	℃			-55 ~+150				

Electrical Characteristics (T=25℃ Unless otherwise specified）

Item	Symbol	Unit	Test Condition	Max
Peak Forward Voltage	V_{FM}	V	I_{FM}=2.0A, Pulse measurement, Rating of per diode	1.20
Peak Reverse Current	I_{RRM}	μA	V_{RM}=V_{RRM} , Pulse measurement, Rating of per diode	5
Thermal Resistance	$R_{\theta J-A}$	℃/W	Between junction and ambient, On alumina substrate	62.5
	$R_{\theta J-L}$		Between junction and lead	25
	$R_{\theta J-C}$		Between junction and case	25

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

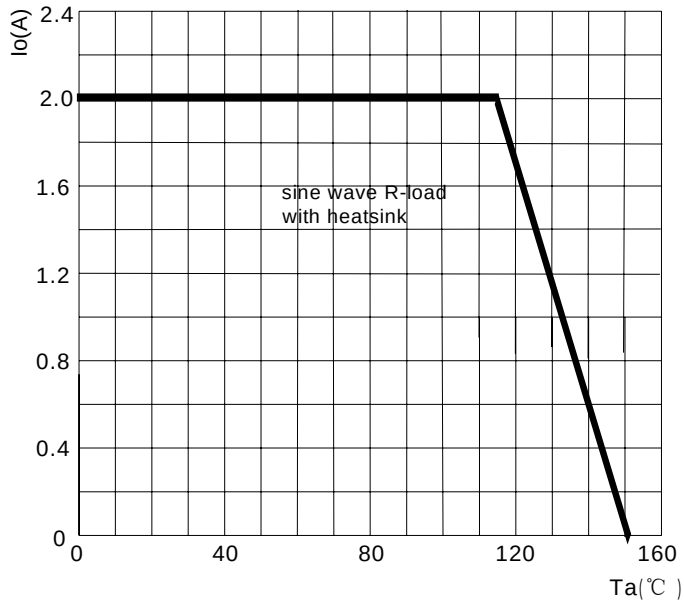


FIG.2:MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

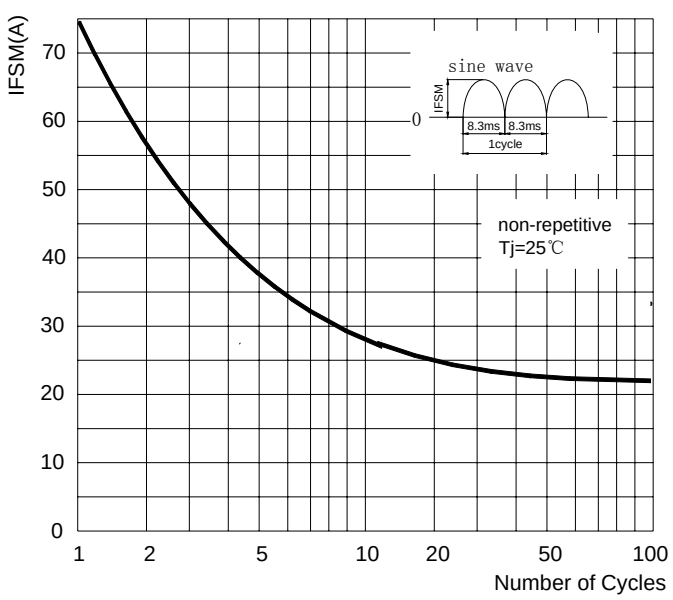


FIG.3: TYPICAL FORWARD CHARACTERISTICS

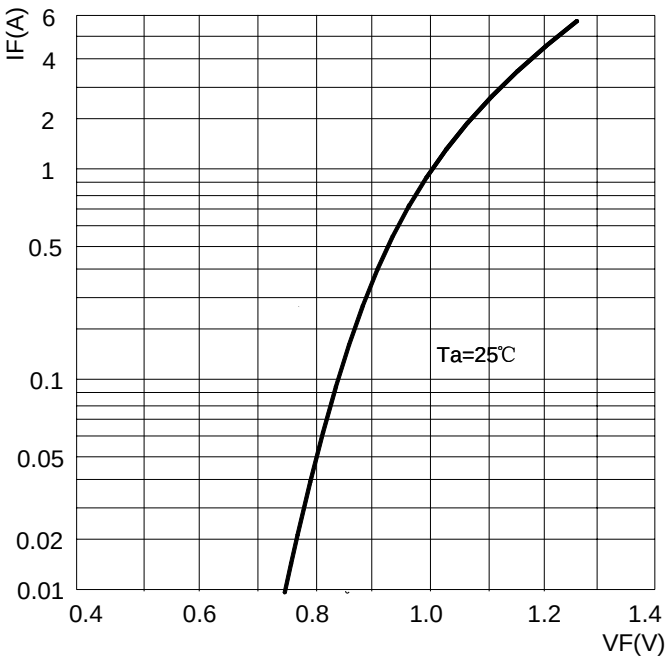


FIG.4:TYPICAL REVERSE CHARACTERISTICS

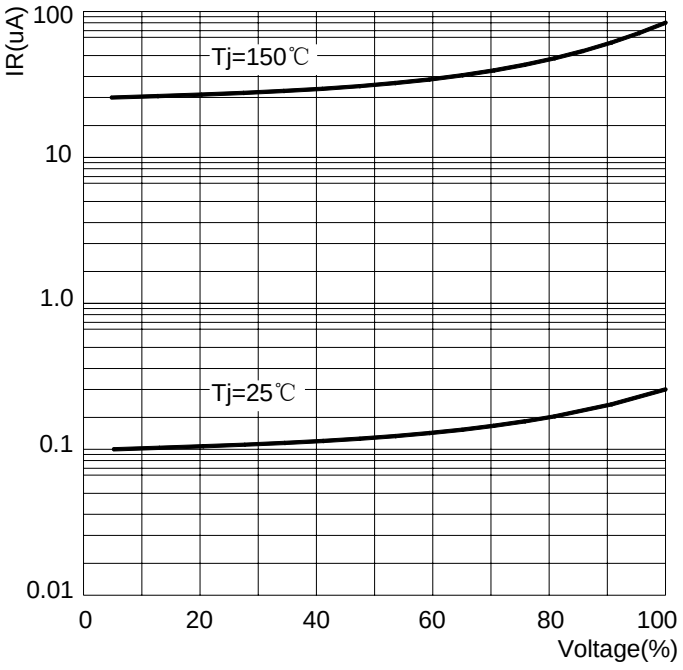
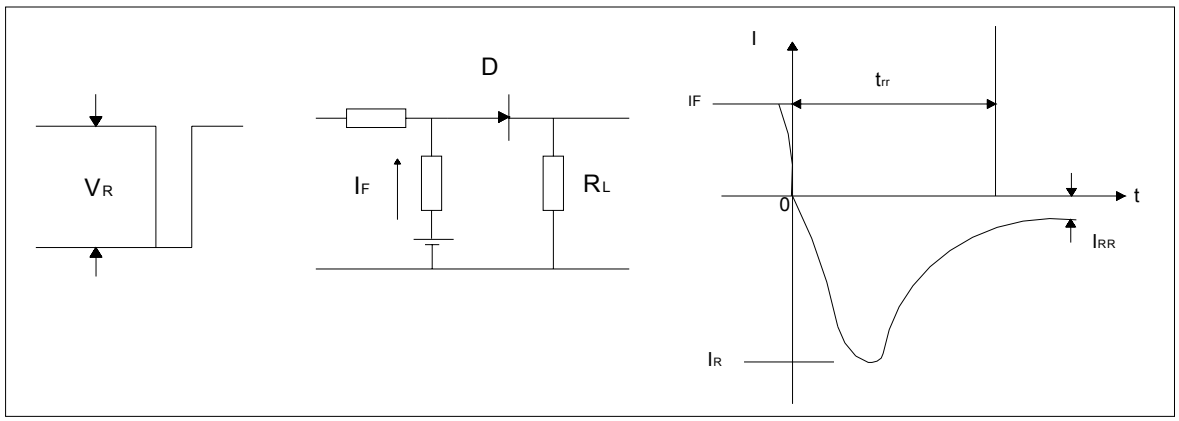
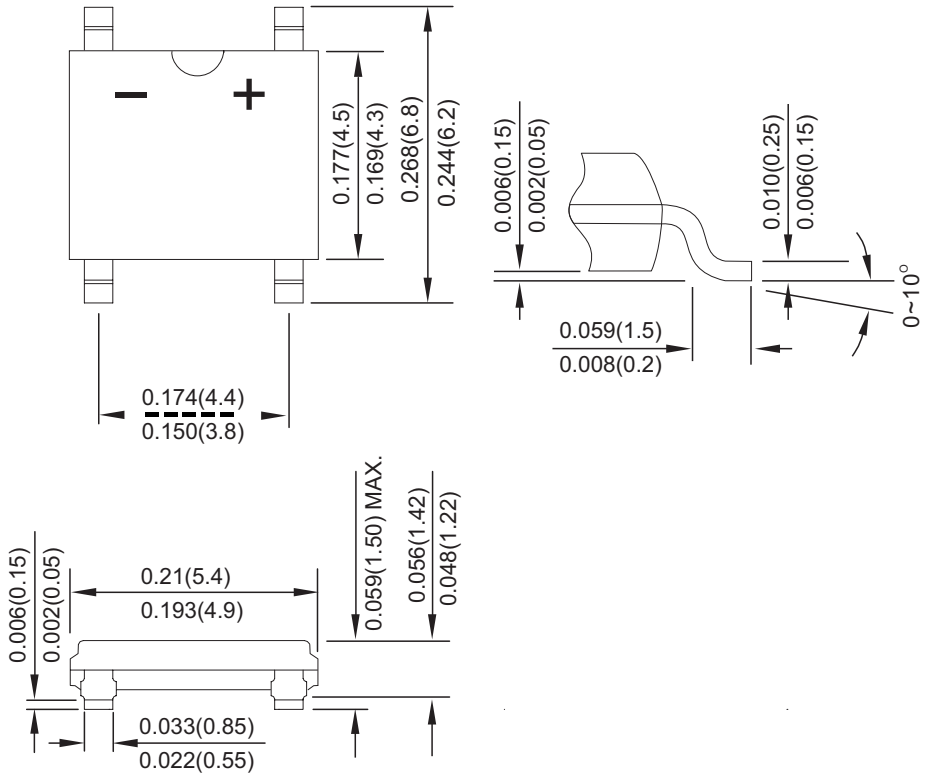


FIG.5: Diagram of circuit and Testing wave form of reverse recovery time

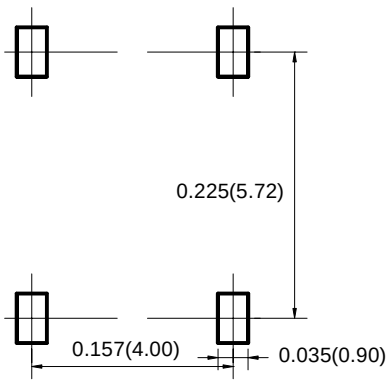


ABS Package Outline Dimensions



Dimensions in inches and (millimeters)

ABS Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

Reel Taping Specifications For Surface Mount Devices-ABS

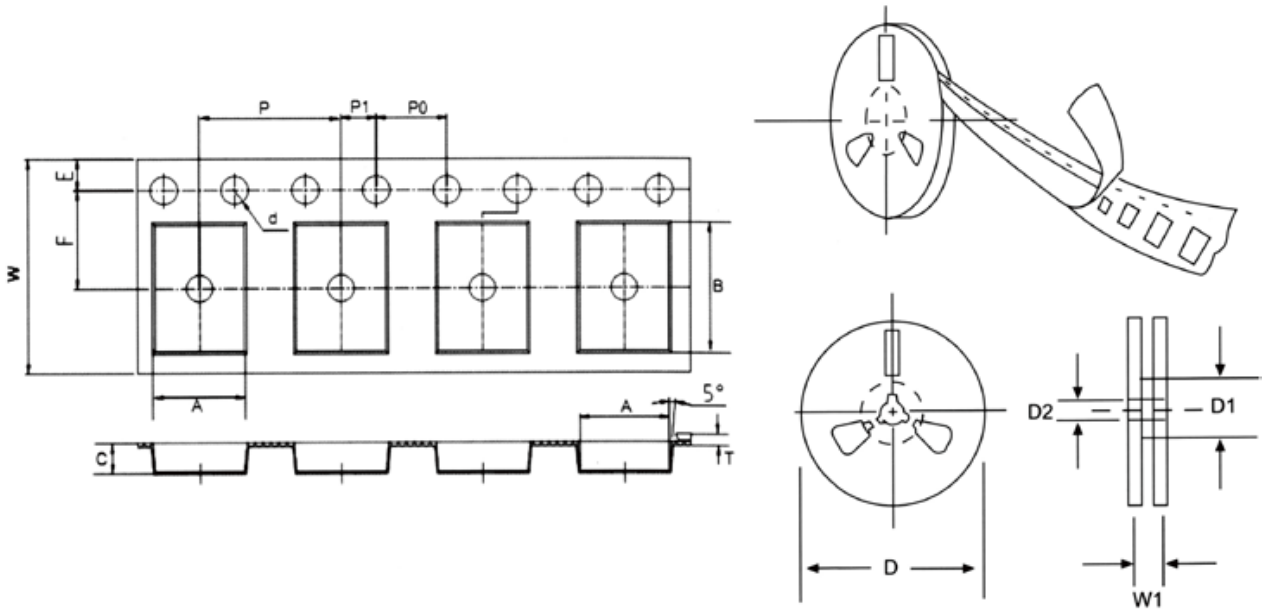


FIG:CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	ABS mm(inch)
Carrier width	A	5.40+0.1(0.213+0.004)
Carrier length	B	6.90+0.05(0.272+0.002)
Carrier depth	C	2.10+0.1(0.083+0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	279±2.0 (11± 0.079)
Reel inner diameter	D1	75 ±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13+0.5(0.512+0.020)
Stroket hole position	E	1.75+0.1(0.069+0.004)
Punch hole position	F	5.5+0.05(0.217+0.002)
Punch hole pitch	P	8.0+0.1(0.315+0.004)
Sprocket hole pitch	P0	4.0+0.1(0.157+0.004)
Embossment center	P1	2.0+0.1(0.079+0.004)
Totall tape thickness	T	0.10-0.70(0.004-0.028)
Tape width	W	12.0+0.3/-0.1(0.472+0.004)
Reel width	W1	16.8+2.0(0.661+0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.